

Section 20 Electrical Characteristics

20.1 Absolute Maximum Ratings

Table 20-1 lists the absolute maximum ratings.

Table 20-1 Absolute Maximum Ratings

—Preliminary—

Item	Symbol	Value	Unit
Power supply voltage	V_{CC}	-0.3 to +7.0	V
Programming voltage	V_{PP}	-0.3 to +13.5	V
Input voltage (except port 7)	V_{IN}	-0.3 to $V_{CC} +0.3$	V
Input voltage (port 7)	V_{IN}	-0.3 to $AV_{CC} +0.3$	V
Reference voltage	V_{REF}	-0.3 to $AV_{CC} +0.3$	V
Analog power supply voltage	AV_{CC}	-0.3 to +7.0	V
Analog input voltage	V_{AN}	-0.3 to $AV_{CC} +0.3$	V
Operating temperature	T_{opr}	Regular specifications: -20 to +75 Wide-range specifications: -40 to +85	°C
Storage temperature	T_{stg}	-55 to +125	°C

Caution: Permanent damage to the chip may result if absolute maximum ratings are exceeded.

20.2 Electrical Characteristics

20.2.1 DC Characteristics

Table 20-2 lists the DC characteristics. Table 20-3 lists the permissible output currents.

Table 20-2 DC Characteristics

Conditions: $V_{CC} = 5.0 \text{ V} \pm 10\%$, $AV_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ V}$ to AV_{CC} ,
 $V_{SS} = AV_{SS} = 0 \text{ V}^*$, $T_a = -20^\circ\text{C}$ to $+75^\circ\text{C}$ (regular specifications),
 $T_a = -40^\circ\text{C}$ to $+85^\circ\text{C}$ (wide-range specifications)

Item		Symbol	Min	Typ	Max	Unit	Test Conditions
Schmitt trigger input voltages	Port A, P8 ₀ to P8 ₂ ,	V_T^-	1.0	—	—	V	
	PB ₀ to PB ₃	V_T^+	—	—	$V_{CC} \times 0.7$	V	
		$V_T^+ - V_T^-$	0.4	—	—	V	
Input high voltage	RES, STBY, NMI, MD ₂ to MD ₀	V_{IH}	$V_{CC} - 0.7$	—	$V_{CC} + 0.3$	V	
	EXTAL		$V_{CC} \times 0.7$	—	$V_{CC} + 0.3$	V	
	Port 7		2.0	—	$AV_{CC} + 0.3 \text{ V}$		
Ports 1, 2, 3, 4, 5, 6, 9, P8 ₃ , P8 ₄ , PB ₄ to PB ₇			2.0	—	$V_{CC} + 0.3$	V	
	RES, STBY, MD ₂ to MD ₀	V_{IL}	-0.3	—	0.5	V	
	NMI, EXTAL, ports 1, 2, 3, 4, 5, 6, 7, 9, P8 ₃ , P8 ₄ , PB ₄ to PB ₇		-0.3	—	0.8	V	
Output high voltage	All output pins	V_{OH}	$V_{CC} - 0.5$	—	—	V	$I_{OH} = -200 \mu\text{A}$
			3.5	—	—	V	$I_{OH} = -1 \text{ mA}$

Note: * If the A/D and D/A converters are not used, do not leave the AV_{CC} , AV_{SS} , and V_{REF} pins open. Connect AV_{CC} and V_{REF} to V_{CC} , and connect AV_{SS} to V_{SS} .

Table 20-2 DC Characteristics (cont)

Conditions: $V_{CC} = 5.0 \text{ V} \pm 10\%$, $AV_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ V}$ to AV_{CC} ,
 $V_{SS} = AV_{SS} = 0 \text{ V}^*$ ¹, $T_a = -20^\circ\text{C}$ to $+75^\circ\text{C}$ (regular specifications),
 $T_a = -40^\circ\text{C}$ to $+85^\circ\text{C}$ (wide-range specifications)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions	
Output low voltage	All output pins (except RESO) V_{OL}	—	—	0.4	V	$I_{OL} = 1.6 \text{ mA}$	
	Ports 1, 2, 5, and B	—	—	1.0	V	$I_{OL} = 10 \text{ mA}$	
	RESO	—	—	0.4	V	$I_{OL} = 2.6 \text{ mA}$	
Input leakage current	STBY, NMI, RES, MD_2 to MD_0	$ I_{IN} $	—	1.0	μA	$V_{IN} = 0.5 \text{ to } V_{CC} - 0.5 \text{ V}$	
	Port 7	—	—	1.0	μA	$V_{IN} = 0.5 \text{ to } AV_{CC} - 0.5 \text{ V}$	
Three-state leakage current (off state)	Ports 1, 2, 3, 4, 5, 6, 8 to B	$ I_{TS1} $	—	1.0	μA	$V_{IN} = 0.5 \text{ to } V_{CC} - 0.5 \text{ V}$	
	RESO	—	—	10.0	μA	$V_{IN} = 0.5 \text{ to } V_{CC} - 0.5 \text{ V}$	
Input pull-up current	Ports 2, 4, and 5	$-I_p$	50	—	μA	$V_{IN} = 0 \text{ V}$	
Input capacitance	NMI	C_{IN}	—	50	pF	$V_{IN} = 0 \text{ V}$ $f = 1 \text{ MHz}$ $T_a = 25^\circ\text{C}$	
	All input pins except NMI	—	—	15	—	—	
Current dissipation ^{*2}	Normal operation	I_{CC}	—	35	mA	$f = 10 \text{ MHz}$	
			—	40	mA	$f = 12 \text{ MHz}$	
			—	50	mA	$f = 16 \text{ MHz}$	
			—	25	mA	$f = 10 \text{ MHz}$	
			—	30	mA	$f = 12 \text{ MHz}$	
	Sleep mode		—	35	mA	$f = 16 \text{ MHz}$	
			—	0.01	μA	$T_a \leq 50^\circ\text{C}$	
			—	—	μA	$50^\circ\text{C} < T_a$	
			—	20.0	—	—	

- Notes:
- If the A/D and D/A converters are not used, do not leave the AV_{CC} , AV_{SS} , and V_{REF} pins open. Connect AV_{CC} and V_{REF} to V_{CC} , and connect AV_{SS} to V_{SS} .
 - Current dissipation values are for $V_{IHmin} = V_{CC} - 0.5 \text{ V}$ and $V_{ILmax} = 0.5 \text{ V}$ with all output pins unloaded and the on-chip pull-up transistors in the off state.
 - The values are for $V_{RAM} \leq V_{CC} < 4.5 \text{ V}$, $V_{IHmin} = V_{CC} \times 0.9$, and $V_{ILmax} = 0.3 \text{ V}$.

Table 20-2 DC Characteristics (cont)

Conditions: $V_{CC} = 5.0 \text{ V} \pm 10\%$, $AV_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ V}$ to AV_{CC} ,
 $V_{SS} = AV_{SS} = 0 \text{ V}$ ¹, $T_a = -20^\circ\text{C}$ to $+75^\circ\text{C}$ (regular specifications),
 $T_a = -40^\circ\text{C}$ to $+85^\circ\text{C}$ (wide-range specifications)

Item		Symbol	Min	Typ	Max	Unit	Test Conditions
Analog power supply current	During A/D conversion	A_{Icc}	—	1.2	2.0	mA	
	During A/D and D/A conversion		—	2.0	5.0	mA	
	Idle		—	0.01	5.0	μA	
Reference current	During A/D conversion	A_{Icc}	—	0.2	0.5	mA	$V_{REF} = 5.0 \text{ V}$
	During A/D and D/A conversion		—	0.5	1.0	mA	
	Idle		—	0.01	5.0	μA	
RAM standby voltage	V_{RAM}	2.0	—	—	—	V	

- Notes:
- If the A/D and D/A converters are not used, do not leave the AV_{CC} , AV_{SS} , and V_{REF} pins open. Connect AV_{CC} and V_{REF} to V_{CC} , and connect AV_{SS} to V_{SS} .
 - Current dissipation values are for $V_{IHmin} = V_{CC} - 0.5 \text{ V}$ and $V_{ILmax} = 0.5 \text{ V}$ with all output pins unloaded and the on-chip pull-up transistors in the off state.
 - The values are for $V_{RAM} < V_{CC} < 4.5 \text{ V}$, $V_{IHmin} = V_{CC} \times 0.9$, and $V_{ILmax} = 0.3 \text{ V}$.

Table 20-2 DC Characteristics (cont)

Conditions: $V_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $AV_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $V_{REF} = 2.7 \text{ V to } AV_{CC}$,
 $V_{SS} = AV_{SS} = 0 \text{ V}^*$, $T_a = -20^\circ\text{C to } +75^\circ\text{C}$ (regular specifications),
 $T_a = -40^\circ\text{C to } +85^\circ\text{C}$ (wide-range specifications)

Item		Symbol	Min	Typ	Max	Unit	Test Conditions
Schmitt trigger input voltages	Port A, P8 ₀ to P8 ₂ , PB ₀ to PB ₃	V_T^-	$V_{CC} \times 0.2$	—	—	V	
		V_T^+	—	—	$V_{CC} \times 0.7$	V	
		$V_T^+ - V_T^-$	$V_{CC} \times 0.07$	—	—	V	
Input high voltage	\overline{RES} , \overline{STBY} , NMI, MD ₂ to MD ₀	V_{IH}	$V_{CC} \times 0.9$	—	$V_{CC} + 0.3$	V	
	EXTAL		$V_{CC} \times 0.7$	—	$V_{CC} + 0.3$	V	
	Port 7		$V_{CC} \times 0.7$	—	$AV_{CC} + 0.3$	V	
	Ports 1, 2, 3, 4, 5, 6, 9, P8 ₃ , P8 ₄ , PB ₄ to PB ₇		$V_{CC} \times 0.7$	—	$V_{CC} + 0.3$	V	
Input low voltage	\overline{RES} , \overline{STBY} , MD ₂ to MD ₀	V_{IL}	-0.3	—	$V_{CC} \times 0.1$	V	
	NMI, EXTAL, ports 1, 2, 3, 4, 5, 6, 7, 9, P8 ₃ , P8 ₄ , PB ₄ to PB ₇		-0.3	—	$V_{CC} \times 0.2$	V	$V_{CC} < 4.0 \text{ V}$
					0.8	V	$V_{CC} = 4.0 \text{ V to } 5.5 \text{ V}$
Output high voltage	All output pins	V_{OH}	$V_{CC} - 0.5$	—	—	V	$I_{OH} = -200 \mu\text{A}$
			$V_{CC} - 1.0$	—	—	V	$I_{OH} = -1 \text{ mA}$
Output low voltage	All output pins (except \overline{RESO})	V_{OL}	—	—	0.4	V	$I_{OL} = 1.6 \text{ mA}$
	Ports 1, 2, 5, and B		—	—	1.0	V	$V_{CC} \leq 4 \text{ V}$ $I_{OL} = 8 \text{ mA}$, $4 \text{ V} < V_{CC} \leq 5.5 \text{ V}$ $I_{OL} = 10 \text{ mA}$
	\overline{RESO}		—	—	0.4	V	$I_{OL} = 2.6 \text{ mA}$
Input leakage current	STBY, NMI, \overline{RES} , MD ₂ to MD ₀	$ I_{IN} $	—	—	1.0	μA	$V_{IN} = 0.5 \text{ to } V_{CC} - 0.5 \text{ V}$
	Port 7		—	—	1.0	μA	$V_{IN} = 0.5 \text{ to } AV_{CC} - 0.5 \text{ V}$

Note: * If the A/D and D/A converters are not used, do not leave the AV_{CC} , AV_{SS} , and V_{REF} pins open. Connect AV_{CC} and V_{REF} to V_{CC} , and connect AV_{SS} to V_{SS} .

Table 20-2 DC Characteristics (cont)

Conditions: $V_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $AV_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $V_{REF} = 2.7 \text{ V to } AV_{CC}$,
 $V_{SS} = AV_{SS} = 0 \text{ V}^*$ ¹, $T_a = -20^\circ\text{C to } +75^\circ\text{C}$ (regular specifications),
 $T_a = -40^\circ\text{C to } +85^\circ\text{C}$ (wide-range specifications)

Item		Symbol	Min	Typ	Max	Unit	Test Conditions
Three-state leakage current (off state)	Ports 1, 2, 3, 4, 5, 6, 8 to B	$ I_{TS1} $	—	—	1.0	μA	$V_{IN} = 0.5 \text{ to } V_{CC} - 0.5 \text{ V}$
	\overline{RESO}		—	—	10.0	μA	$V_{IN} = 0.5 \text{ to } V_{CC} - 0.5 \text{ V}$
Input pull-up current	Ports 2, 4, and 5	$-I_p$	10	—	300	μA	$V_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $V_{IN} = 0 \text{ V}$
Input capacitance	NMI	C_{IN}	—	—	50	pF	$V_{IN} = 0 \text{ V}$ $f = 1 \text{ MHz}$ $T_a = 25^\circ\text{C}$
Current dissipation ^{*2}	Normal operation	I_{CC}^{*4}	—	30 (5.0 V)	36.2 (5.5 V)	mA	$f = 8 \text{ MHz}$
	Sleep mode		—	20 (5.0 V)	27.4 (5.5 V)	mA	$f = 8 \text{ MHz}$
	Standby mode ^{*3}		—	0.01	5.0	μA	$T_a \leq 50^\circ\text{C}$
			—	—	20.0	μA	$50^\circ\text{C} < T_a$
Analog power supply current	During A/D conversion	A_{Icc}	—	1.0	2.0	mA	$AV_{CC} = 3.0 \text{ V}$
			—	1.2	—	mA	$AV_{CC} = 5.0 \text{ V}$
	During A/D and D/A conversion		—	1.8	4.0	mA	$AV_{CC} = 3.0 \text{ V}$
	Idle		—	2.0	—	mA	$AV_{CC} = 5.0 \text{ V}$
			—	0.01	5.0	μA	

- Notes:
- If the A/D and D/A converters are not used, do not leave the AV_{CC} , AV_{SS} , and V_{REF} pins open. Connect AV_{CC} and V_{REF} to V_{CC} , and connect AV_{SS} to V_{SS} .
 - Current dissipation values are for $V_{IHmin} = V_{CC} - 0.5 \text{ V}$ and $V_{ILmax} = 0.5 \text{ V}$ with all output pins unloaded and the on-chip pull-up transistors in the off state.
 - The values are for $V_{RAM} \leq V_{CC} < 2.7 \text{ V}$, $V_{IHmin} = V_{CC} \times 0.9$, and $V_{ILmax} = 0.3 \text{ V}$.
 - I_{CC} depends on V_{CC} and f as follows:
 $I_{CCmax} = 1.0 \text{ (mA)} + 0.8 \text{ (mA/MHz} \cdot \text{V}) \times V_{CC} \times f$ [normal mode]
 $I_{CCmax} = 1.0 \text{ (mA)} + 0.6 \text{ (mA/MHz} \cdot \text{V}) \times V_{CC} \times f$ [sleep mode]

Table 20-2 DC Characteristics (cont)

Conditions: $V_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $AV_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $V_{REF} = 2.7 \text{ V to } AV_{CC}$,
 $V_{SS} = AV_{SS} = 0 \text{ V}^*$, $T_a = -20^\circ\text{C to } +75^\circ\text{C}$ (regular specifications),
 $T_a = -40^\circ\text{C to } +85^\circ\text{C}$ (wide-range specifications)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Reference current	During A/D conversion	—	0.1	0.2	mA	$V_{REF} = 3.0 \text{ V}$
		—	0.2	—	mA	$V_{REF} = 5.0 \text{ V}$
	During A/D and D/A conversion	—	0.2	0.4	mA	$V_{REF} = 3.0 \text{ V}$
		—	0.5	—	mA	$V_{REF} = 5.0 \text{ V}$
Idle	—	—	0.01	5.0	μA	
RAM standby voltage	V_{RAM}	2.0	—	—	V	

Note: * If the A/D and D/A converters are not used, do not leave the AV_{CC} , AV_{SS} , and V_{REF} pins open. Connect AV_{CC} and V_{REF} to V_{CC} , and connect AV_{SS} to V_{SS} .

Table 20-3 Permissible Output Currents

Conditions: $V_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $AV_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $V_{REF} = 2.7 \text{ V to } AV_{CC}$,
 $V_{SS} = AV_{SS} = 0 \text{ V}$, $T_a = -20^\circ\text{C to } +75^\circ\text{C}$ (regular specifications),
 $T_a = -40^\circ\text{C to } +85^\circ\text{C}$ (wide-range specifications)

Item	Symbol	Min	Typ	Max	Unit
Permissible output low current (per pin)	Ports 1, 2, 5, and B	I_{OL}	—	—	10 mA
	Other output pins	—	—	2.0	mA
Permissible output low current (total)	Total of 28 pins in ports 1, 2, 5, and B	ΣI_{OL}	—	—	80 mA
	Total of all output pins, including the above	—	—	120	mA
Permissible output high current (per pin)	All output pins	I_{OH}	—	—	2.0 mA
Permissible output high current (total)	Total of all output pins	ΣI_{OH}	—	—	40 mA

Notes: 1. To protect chip reliability, do not exceed the output current values in table 20-3.
2. When driving a darlington pair or LED, always insert a current-limiting resistor in the output line, as shown in figures 20-1 and 20-2.

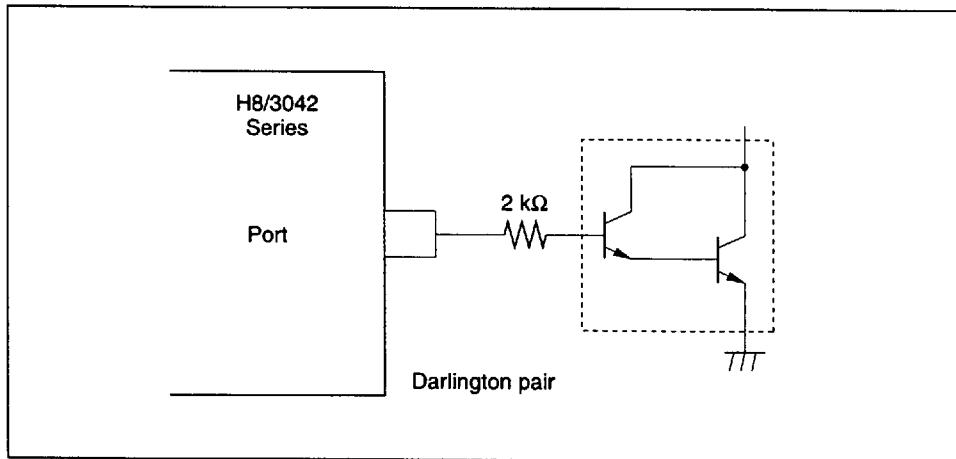


Figure 20-1 Darlington Pair Drive Circuit (Example)

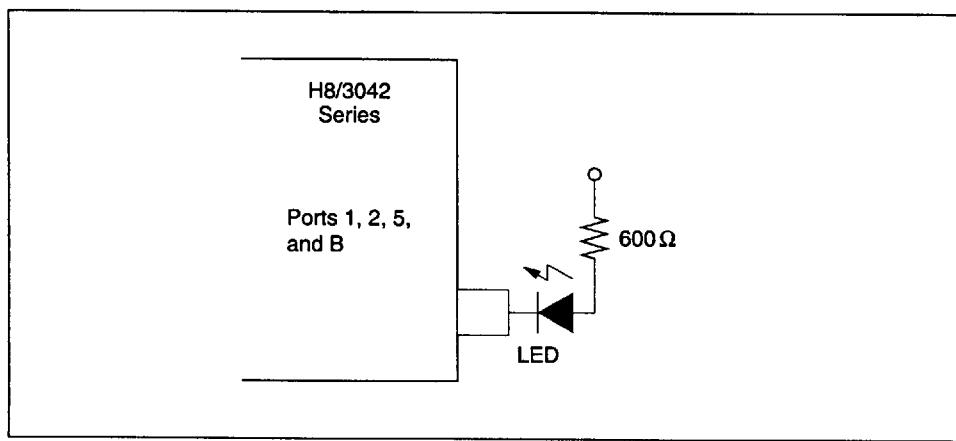


Figure 20-2 LED Drive Circuit (Example)

20.2.2 AC Characteristics

Bus timing parameters are listed in table 20-4. Refresh controller bus timing parameters are listed in table 20-5. Control signal timing parameters are listed in table 20-6. Timing parameters of the on-chip supporting modules are listed in table 20-7.

Table 20-4 Bus Timing (1)

Condition A: $V_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $AV_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $V_{REF} = 2.7 \text{ V to } AV_{CC}$,
 $V_{SS} = AV_{CC} = 0 \text{ V}$, $\phi = 2 \text{ MHz to } 8 \text{ MHz}$, $T_a = -20^\circ\text{C to } +75^\circ\text{C}$ (regular specifications), $T_a = -40^\circ\text{C to } +85^\circ\text{C}$ (wide-range specifications)

Condition B: $V_{CC} = 5.0 \text{ V} \pm 10\%$, $AV_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ V to } AV_{CC}$,
 $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 2 \text{ MHz to } 16 \text{ MHz}$, $T_a = -20^\circ\text{C to } +75^\circ\text{C}$ (regular specifications), $T_a = -40^\circ\text{C to } +85^\circ\text{C}$ (wide-range specifications)

Item	Symbol	Condition A		Condition B				Test Unit	Conditions
		8 MHz	10 MHz	12 MHz	16 MHz				
Clock cycle time	t_{CYC}	125	500	100	500	83.3	500	62.5	500
Clock rise time	t_{CR}	—	20	—	10	—	10	—	10
Clock fall time	t_{CF}	—	20	—	10	—	10	—	10
Address delay time	t_{AD}	—	60	—	40	—	35	—	30
Address hold time	t_{AH}	25	—	20	—	15	—	10	—
Address strobe delay time	t_{ASD}	—	60	—	40	—	35	—	30
Write strobe delay time	t_{WSD}	—	60	—	40	—	35	—	30
Strobe delay time	t_{SD}	—	60	—	40	—	35	—	30
Write data strobe pulse width 1	t_{WSW1*}	85	—	70	—	55	—	35	—
Write data strobe pulse width 2	t_{WSW2*}	150	—	120	—	95	—	65	—
Address setup time 1	t_{AS1}	20	—	15	—	10	—	10	—
Address setup time 2	t_{AS2}	80	—	65	—	50	—	40	—
Read data setup time	t_{RDS}	50	—	20	—	20	—	20	—
Read data hold time	t_{RDH}	0	—	0	—	0	—	0	—

Table 20-4 Bus Timing (cont)

Condition A: $V_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $AV_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $V_{REF} = 2.7 \text{ V to } AV_{CC}$,
 $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 2 \text{ MHz to } 8 \text{ MHz}$, $T_a = -20^\circ\text{C to } +75^\circ\text{C}$ (regular
specifications), $T_a = -40^\circ\text{C to } +85^\circ\text{C}$ (wide-range specifications)

Condition B: $V_{CC} = 5.0 \text{ V} \pm 10\%$, $AV_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ V to } AV_{CC}$,
 $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 2 \text{ MHz to } 16 \text{ MHz}$, $T_a = -20^\circ\text{C to } +75^\circ\text{C}$ (regular
specifications), $T_a = -40^\circ\text{C to } +85^\circ\text{C}$ (wide-range specifications)

Item	Symbol	Condition A				Condition B				Test Conditions	
		8 MHz		10 MHz		12 MHz		16 MHz			
		Min	Max	Min	Max	Min	Max	Min	Max		
Write data delay time	t_{WDD}	—	75	—	65	—	60	—	60	ns	
Write data setup time 1	t_{WDS1}	90	—	75	—	60	—	35	—	Figure 20-4, Figure 20-5	
Write data setup time 2	t_{WDS2}	15	—	10	—	10	—	5	—		
Write data hold time	t_{WDH}	25	—	20	—	20	—	20	—		
Read data access time 1	t_{ACC1*}	—	110	—	100	—	80	—	55		
Read data access time 2	t_{ACC2*}	—	230	—	200	—	160	—	115		
Read data access time 3	t_{ACC3*}	—	55	—	50	—	40	—	25		
Read data access time 4	t_{ACC4*}	—	160	—	150	—	120	—	85		
Precharge time	t_{PCH*}	85	—	70	—	55	—	40	—		
Wait setup time	t_{WTS}	40	—	35	—	25	—	25	—	ns	
Wait hold time	t_{WTH}	10	—	10	—	5	—	5	—		
Bus request setup time	t_{BROS}	40	—	40	—	40	—	40	—	ns	
Bus acknowledge delay time 1	t_{BACD1}	—	60	—	50	—	40	—	30	Figure 20-18	
Bus acknowledge delay time 2	t_{BACD2}	—	60	—	50	—	40	—	30		
Bus-floating time	t_{BZD}	—	70	—	60	—	50	—	40		

Note is on next page.

Note: At 8 MHz, the times below depend as indicated on the clock cycle time.

$$\begin{array}{ll} t_{ACC1} = 1.5 \times t_{cyc} - 78 \text{ (ns)} & t_{WSW1} = 1.0 \times t_{cyc} - 40 \text{ (ns)} \\ t_{ACC2} = 2.5 \times t_{cyc} - 83 \text{ (ns)} & t_{WSW2} = 1.5 \times t_{cyc} - 38 \text{ (ns)} \\ t_{ACC3} = 1.0 \times t_{cyc} - 70 \text{ (ns)} & t_{PCH} = 1.0 \times t_{cyc} - 40 \text{ (ns)} \\ t_{ACC4} = 2.0 \times t_{cyc} - 90 \text{ (ns)} & \end{array}$$

At 10 MHz, the times below depend as indicated on the clock cycle time.

$$\begin{array}{ll} t_{ACC1} = 1.5 \times t_{cyc} - 50 \text{ (ns)} & t_{WSW1} = 1.0 \times t_{cyc} - 30 \text{ (ns)} \\ t_{ACC2} = 2.5 \times t_{cyc} - 50 \text{ (ns)} & t_{WSW2} = 1.5 \times t_{cyc} - 30 \text{ (ns)} \\ t_{ACC3} = 1.0 \times t_{cyc} - 50 \text{ (ns)} & t_{PCH} = 1.0 \times t_{cyc} - 30 \text{ (ns)} \\ t_{ACC4} = 2.0 \times t_{cyc} - 50 \text{ (ns)} & \end{array}$$

At 12 MHz, the times below depend as indicated on the clock cycle time.

$$\begin{array}{ll} t_{ACC1} = 1.5 \times t_{cyc} - 45 \text{ (ns)} & t_{WSW1} = 1.0 \times t_{cyc} - 28 \text{ (ns)} \\ t_{ACC2} = 2.5 \times t_{cyc} - 48 \text{ (ns)} & t_{WSW2} = 1.5 \times t_{cyc} - 30 \text{ (ns)} \\ t_{ACC3} = 1.0 \times t_{cyc} - 43 \text{ (ns)} & t_{PCH} = 1.0 \times t_{cyc} - 28 \text{ (ns)} \\ t_{ACC4} = 2.0 \times t_{cyc} - 47 \text{ (ns)} & \end{array}$$

At 16 MHz, the times below depend as indicated on the clock cycle time.

$$\begin{array}{ll} t_{ACC1} = 1.5 \times t_{cyc} - 39 \text{ (ns)} & t_{WSW1} = 1.0 \times t_{cyc} - 28 \text{ (ns)} \\ t_{ACC2} = 2.5 \times t_{cyc} - 41 \text{ (ns)} & t_{WSW2} = 1.5 \times t_{cyc} - 28 \text{ (ns)} \\ t_{ACC3} = 1.0 \times t_{cyc} - 38 \text{ (ns)} & t_{PCH} = 1.0 \times t_{cyc} - 23 \text{ (ns)} \\ t_{ACC4} = 2.0 \times t_{cyc} - 40 \text{ (ns)} & \end{array}$$

Table 20-5 Refresh Controller Bus Timing

Condition A: $V_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $AV_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $V_{REF} = 2.7 \text{ V to } AV_{CC}$,
 $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 2 \text{ MHz to } 8 \text{ MHz}$, $T_a = -20^\circ\text{C to } +75^\circ\text{C}$ (regular specifications), $T_a = -40^\circ\text{C to } +85^\circ\text{C}$ (wide-range specifications)

Condition B: $V_{CC} = 5.0 \text{ V} \pm 10\%$, $AV_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ V to } AV_{CC}$,
 $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 2 \text{ MHz to } 16 \text{ MHz}$, $T_a = -20^\circ\text{C to } +75^\circ\text{C}$ (regular specifications), $T_a = -40^\circ\text{C to } +85^\circ\text{C}$ (wide-range specifications)

Item	Symbol	Condition A		Condition B				Test Conditions
		8 MHz	10 MHz	12 MHz	16 MHz	Min	Max	
RAS delay time 1	t_{RAD1}	—	60	—	30	—	30	ns
RAS delay time 2	t_{RAD2}	—	60	—	30	—	30	
RAS delay time 3	t_{RAD3}	—	60	—	30	—	30	
Row address hold time*	t_{RAH}	25	—	20	—	15	—	15
RAS precharge time*	t_{RP}	85	—	70	—	55	—	40
CAS to RAS precharge time*	t_{CRP}	85	—	70	—	55	—	40
CAS pulse width	t_{CAS}	110	—	40	—	40	—	40
RAS access time*	t_{RAC}	—	160	—	150	—	120	—
Address access time	t_{AA}	—	105	—	55	—	55	—
CAS access time*	t_{CAC}	—	50	—	50	—	40	—
Write data setup time 3	t_{WDS3}	75	—	40	—	40	—	40
CAS setup time*	t_{CSR}	20	—	15	—	15	—	15
Read strobe delay time	t_{RSD}	—	60	—	30	—	30	—

Note: At 8 MHz, the times below depend as indicated on the clock cycle time.

$$t_{RAH} = 0.5 \times t_{cyc} - 38 \text{ (ns)} \quad t_{CAC} = 1.0 \times t_{cyc} - 75 \text{ (ns)}$$

$$t_{RAC} = 2.0 \times t_{cyc} - 90 \text{ (ns)} \quad t_{CSR} = 0.5 \times t_{cyc} - 43 \text{ (ns)}$$

$$t_{RP} = t_{CRP} = 1.0 \times t_{cyc} - 40 \text{ (ns)}$$

At 10 MHz, the times below depend as indicated on the clock cycle time.

$$t_{RAH} = 0.5 \times t_{cyc} - 30 \text{ (ns)} \quad t_{CAC} = 1.0 \times t_{cyc} - 50 \text{ (ns)}$$

$$t_{RAC} = 2.0 \times t_{cyc} - 50 \text{ (ns)} \quad t_{CSR} = 0.5 \times t_{cyc} - 35 \text{ (ns)}$$

$$t_{RP} = t_{CRP} = 1.0 \times t_{cyc} - 30 \text{ (ns)}$$

At 12 MHz, the times below depend as indicated on the clock cycle time.

$$t_{RAH} = 0.5 \times t_{cyc} - 27 \text{ (ns)} \quad t_{CAC} = 1.0 \times t_{cyc} - 43 \text{ (ns)}$$

$$t_{RAC} = 2.0 \times t_{cyc} - 47 \text{ (ns)} \quad t_{CSR} = 0.5 \times t_{cyc} - 27 \text{ (ns)}$$

$$t_{RP} = t_{CRP} = 1.0 \times t_{cyc} - 28 \text{ (ns)}$$

At 16 MHz, the times below depend as indicated on the clock cycle time.

$$t_{RAH} = 0.5 \times t_{cyc} - 16 \text{ (ns)} \quad t_{CAC} = 1.0 \times t_{cyc} - 38 \text{ (ns)}$$

$$t_{RAC} = 2.0 \times t_{cyc} - 40 \text{ (ns)} \quad t_{CSR} = 0.5 \times t_{cyc} - 16 \text{ (ns)}$$

$$t_{RP} = t_{CRP} = 1.0 \times t_{cyc} - 23 \text{ (ns)}$$

Table 20-6 Control Signal Timing

Condition A: $V_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $AV_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $V_{REF} = 2.7 \text{ V to } AV_{CC}$,
 $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 2 \text{ MHz to } 8 \text{ MHz}$, $T_a = -20^\circ\text{C to } +75^\circ\text{C}$ (regular specifications), $T_a = -40^\circ\text{C to } +85^\circ\text{C}$ (wide-range specifications)

Condition B: $V_{CC} = 5.0 \text{ V} \pm 10\%$, $AV_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ V to } AV_{CC}$,
 $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 2 \text{ MHz to } 16 \text{ MHz}$, $T_a = -20^\circ\text{C to } +75^\circ\text{C}$ (regular specifications), $T_a = -40^\circ\text{C to } +85^\circ\text{C}$ (wide-range specifications)

Item	Symbol	Condition A				Condition B				Test Unit	Conditions
		8 MHz		10 MHz		12 MHz		16 MHz			
		Min	Max	Min	Max	Min	Max	Min	Max		
RES setup time	t_{RESS}	200	—	200	—	200	—	200	—	ns	Figure 20-15
RES pulse width	t_{RESW}	10	—	10	—	10	—	10	—	t_{CYC}	
RESO output delay time	t_{RESD}	—	100	—	100	—	100	—	100	ns	Figure 20-16
RESO output pulse width	t_{RESOW}	132	—	132	—	132	—	132	—	t_{CYC}	
NMI setup time (NMI, $\overline{IRQ_5}$ to $\overline{IRQ_0}$)	t_{NMIS}	150	—	150	—	150	—	150	—	ns	Figure 20-17
NMI hold time (NMI, $\overline{IRQ_5}$ to $\overline{IRQ_0}$)	t_{NMIH}	10	—	10	—	10	—	10	—		
Interrupt pulse width (NMI, $\overline{IRQ_2}$ to $\overline{IRQ_0}$ when exiting software standby mode)	t_{NMIW}	200	—	200	—	200	—	200	—		
Clock oscillator settling time at reset (crystal)	t_{OSC1}	20	—	20	—	20	—	20	—	ms	Figure 20-19
Clock oscillator settling time in software standby (crystal)	t_{OSC2}	8	—	8	—	8	—	8	—	ms	Figure 19-1

Table 20-7 Timing of On-Chip Supporting Modules

Condition A: $V_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $AV_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $V_{REF} = 2.7 \text{ V to } AV_{CC}$,
 $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 2 \text{ MHz to } 8 \text{ MHz}$, $T_a = -20^\circ\text{C to } +75^\circ\text{C}$ (regular specifications), $T_a = -40^\circ\text{C to } +85^\circ\text{C}$ (wide-range specifications)

Condition B: $V_{CC} = 5.0 \text{ V} \pm 10\%$, $AV_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ V to } AV_{CC}$,
 $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 2 \text{ MHz to } 16 \text{ MHz}$, $T_a = -20^\circ\text{C to } +75^\circ\text{C}$ (regular specifications), $T_a = -40^\circ\text{C to } +85^\circ\text{C}$ (wide-range specifications)

Item	Symbol	Condition A				Condition B				Test Conditions		
		8 MHz		10 MHz		12 MHz		16 MHz				
		Min	Max	Min	Max	Min	Max	Min	Max			
DMAC	t_{DREQ} setup time	t_{DROS}	40	—	30	—	30	—	30	ns	Figure 20-27	
	t_{DREQ} hold time	t_{DRQH}	10	—	10	—	10	—	10	—		
	$TEND$ delay time 1	t_{TED1}	—	100	—	50	—	50	—	50	Figure 20-25, Figure 20-26	
	$TEND$ delay time 2	t_{TED2}	—	100	—	50	—	50	—	50		
ITU	Timer output delay time	t_{TOCD}	—	100	—	100	—	100	—	100	ns	Figure 20-21
	Timer input setup time	t_{TICS}	50	—	50	—	50	—	50	—		
	Timer clock input setup time	t_{TCKS}	50	—	50	—	50	—	50	—	Figure 20-22	
	Timer clock pulse width	Single edge	t_{TCKWH}	1.5	—	1.5	—	1.5	—	1.5	t_{Cyc}	
	Both edges	t_{TCKWL}	2.5	—	2.5	—	2.5	—	2.5	—		
SCI	Input clock cycle	Asynchronous	t_{SCYC}	4	—	4	—	4	—	4	t_{Cyc}	Figure 20-23
	Synchronous	t_{SCYC}	6	—	6	—	6	—	6	—		
	Input clock rise time	t_{SCKR}	—	1.5	—	1.5	—	1.5	—	1.5	t_{SCYC}	
	Input clock fall time	t_{SCKF}	—	1.5	—	1.5	—	1.5	—	1.5		
	Input clock pulse width	t_{SCKW}	0.4	0.6	0.4	0.6	0.4	0.6	0.4	0.6		

Table 20-7 Timing of On-Chip Supporting Modules (cont)

Condition A: $V_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $AV_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $V_{REF} = 2.7 \text{ V to } AV_{CC}$,
 $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 2 \text{ MHz to } 8 \text{ MHz}$, $T_a = -20^\circ\text{C to } +75^\circ\text{C}$ (regular specifications), $T_a = -40^\circ\text{C to } +85^\circ\text{C}$ (wide-range specifications)

Condition B: $V_{CC} = 5.0 \text{ V} \pm 10\%$, $AV_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ V to } AV_{CC}$,
 $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 2 \text{ MHz to } 16 \text{ MHz}$, $T_a = -20^\circ\text{C to } +75^\circ\text{C}$ (regular specifications), $T_a = -40^\circ\text{C to } +85^\circ\text{C}$ (wide-range specifications)

Item	Symbol	Condition A				Condition B				Test Conditions	
		8 MHz		10 MHz		12 MHz		16 MHz			
		Min	Max	Min	Max	Min	Max	Min	Max		
SCI	t _{TXD}	—	100	—	100	—	100	—	100	ns Figure 20-24	
	t _{RXS}	100	—	100	—	100	—	100	—		
	t _{TRXH}	100	—	100	—	100	—	100	—		
	t _{PRH}	0	—	0	—	0	—	0	—		
Ports	t _{PWD}	—	100	—	100	—	100	—	100	ns Figure 20-20	
TPC	t _{PRAS}	50	—	50	—	50	—	50	—		
	t _{PRH}	50	—	50	—	50	—	50	—		

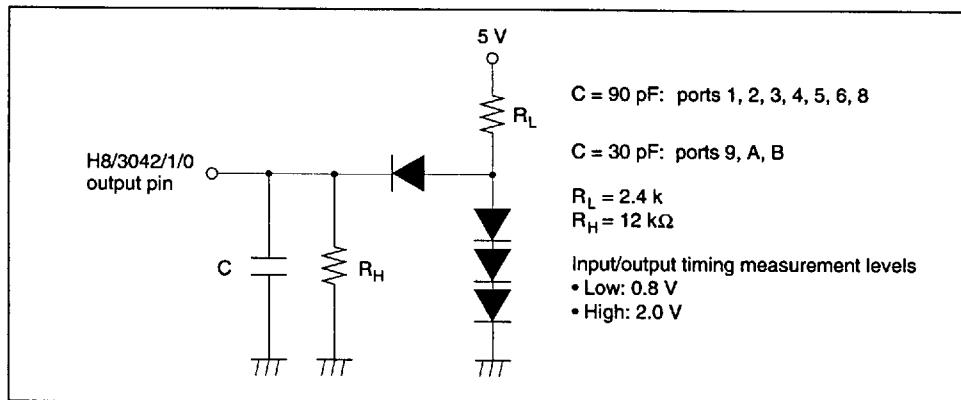


Figure 20-3 Output Load Circuit

20.2.3 A/D Conversion Characteristics

Table 20-8 lists the A/D conversion characteristics.

Table 20-8 A/D Converter Characteristics

Condition A: $V_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $AV_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $V_{REF} = 2.7 \text{ V to } AV_{CC}$,
 $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 2 \text{ MHz to } 8 \text{ MHz}$, $T_a = -20^\circ\text{C to } +75^\circ\text{C}$ (regular specifications), $T_a = -40^\circ\text{C to } +85^\circ\text{C}$ (wide-range specifications)

Condition B: $V_{CC} = 5.0 \text{ V} \pm 10\%$, $AV_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ V to } AV_{CC}$,
 $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 2 \text{ MHz to } 16 \text{ MHz}$, $T_a = -20^\circ\text{C to } +75^\circ\text{C}$ (regular specifications), $T_a = -40^\circ\text{C to } +85^\circ\text{C}$ (wide-range specifications)

Item	Condition A						Condition B						Unit	
	8 MHz			10 MHz			12 MHz			16 MHz				
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max		
Resolution	10	10	10	10	10	10	10	10	10	10	10	10	bits	
Conversion time	—	—	16.8	—	—	13.4	—	—	11.2	—	—	8.4	μs	
Analog input capacitance	—	—	20	—	—	20	—	—	20	—	—	20	pF	
Permissible signal-source impedance	—	—	10^{*1}	—	—	10	—	—	10	—	—	10^{*3}	kΩ	
	—	—	5^{*2}	—	—	—	—	—	—	—	—	—	5^{*4}	
Nonlinearity error	—	—	± 6.0	—	—	± 3.0	—	—	± 3.0	—	—	± 3.0	LSB	
Offset error	—	—	± 4.0	—	—	± 2.0	—	—	± 2.0	—	—	± 2.0	LSB	
Full-scale error	—	—	± 4.0	—	—	± 2.0	—	—	± 2.0	—	—	± 2.0	LSB	
Quantization error	—	—	± 0.5	—	—	± 0.5	—	—	± 0.5	—	—	± 0.5	LSB	
Absolute accuracy	—	—	± 8.0	—	—	± 4.0	—	—	± 4.0	—	—	± 4.0	LSB	

- Notes:
1. The value is for $4.0 \leq AV_{CC} \leq 5.5$.
 2. The value is for $2.7 \leq AV_{CC} \leq 4.0$.
 3. The value is for $\phi \leq 12 \text{ MHz}$.
 4. The value is for $\phi > 12 \text{ MHz}$.

20.2.4 D/A Conversion Characteristics

Table 20-9 lists the D/A conversion characteristics.

Table 20-9 D/A Converter Characteristics

Condition A: $V_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $AV_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$, $V_{REF} = 2.7 \text{ V to } AV_{CC}$,
 $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 2 \text{ MHz to } 8 \text{ MHz}$, $T_a = -20^\circ\text{C to } +75^\circ\text{C}$
(regular specifications), $T_a = -40^\circ\text{C to } +85^\circ\text{C}$ (wide-range specifications)

Condition B: $V_{CC} = 5.0 \text{ V} \pm 10\%$, $AV_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ V to } AV_{CC}$,
 $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 2 \text{ MHz to } 16 \text{ MHz}$, $T_a = -20^\circ\text{C to } +75^\circ\text{C}$
(regular specifications), $T_a = -40^\circ\text{C to } +85^\circ\text{C}$ (wide-range specifications)

Item	Condition A						Condition B						Test Conditions	
	8 MHz			10 MHz			12 MHz			16 MHz				
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max		
Resolution	8	8	8	8	8	8	8	8	8	8	8	8	Bits	
Conversion time	—	—	10	—	—	10	—	—	10	—	—	10	μs	
Absolute accuracy	—	± 2.0	± 3.0	—	± 1.0	± 1.5	—	± 1.0	± 1.5	—	± 1.0	± 1.5	LSB 2-M Ω resistive load	
	—	—	± 2.0	—	—	± 1.0	—	—	± 1.0	—	—	± 1.0	LSB 4-M Ω resistive load	

20.3 Operational Timing

This section shows timing diagrams.

20.3.1 Bus Timing

Bus timing is shown as follows:

- Basic bus cycle: two-state access

Figure 20-4 shows the timing of the external two-state access cycle.

- Basic bus cycle: three-state access

Figure 20-5 shows the timing of the external three-state access cycle.

- Basic bus cycle: three-state access with one wait state

Figure 20-6 shows the timing of the external three-state access cycle with one wait state inserted.

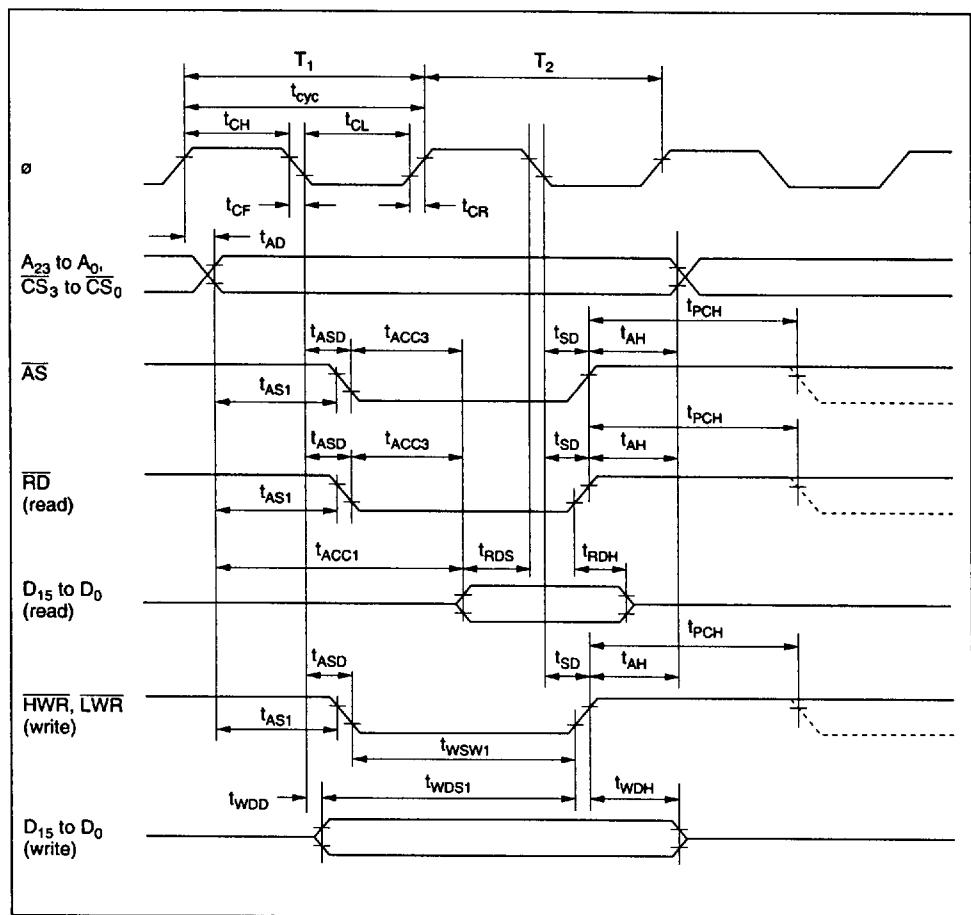


Figure 20-4 Basic Bus Cycle: Two-State Access

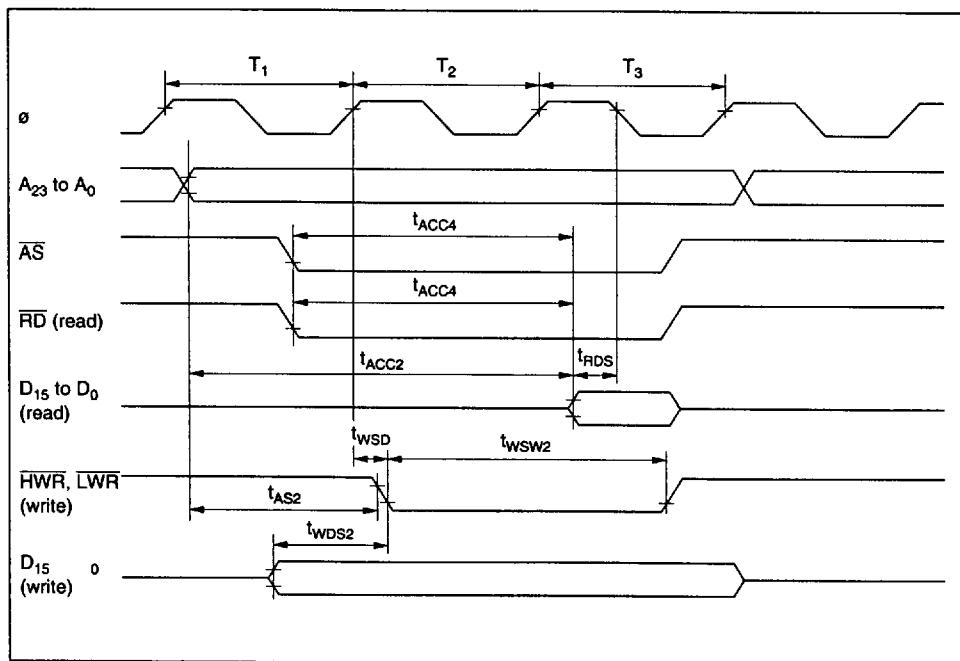


Figure 20-5 Basic Bus Cycle: Three-State Access

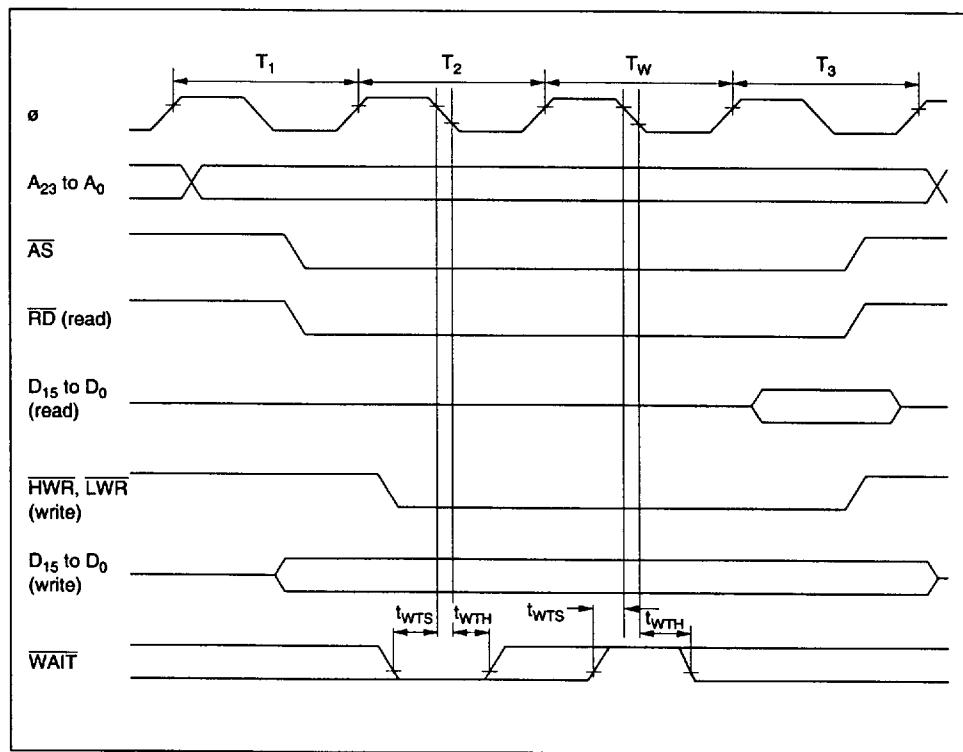


Figure 20-6 Basic Bus Cycle: Three-State Access with One Wait State

20.3.2 Refresh Controller Bus Timing

Refresh controller bus timing is shown as follows:

- DRAM bus timing

Figures 20-7 to 20-12 show the DRAM bus timing in each operating mode.

- PSRAM bus timing

Figures 20-13 and 20-14 show the pseudo-static RAM bus timing in each operating mode.

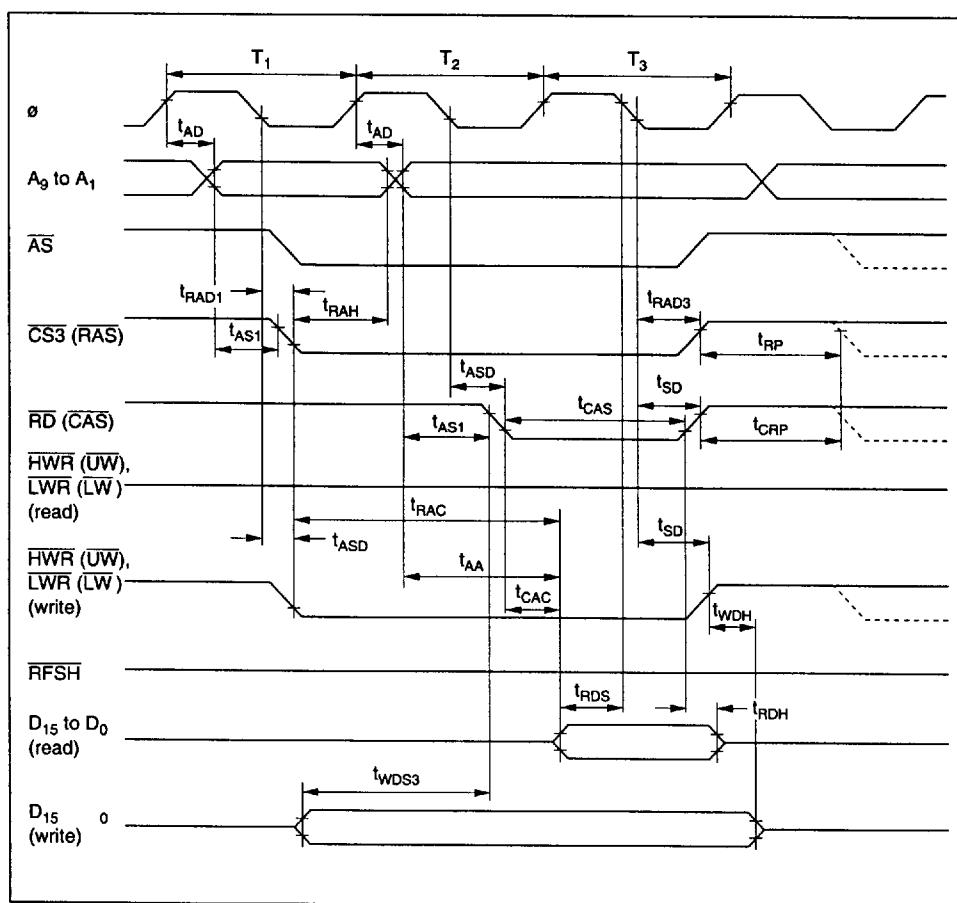


Figure 20-7 DRAM Bus Timing (Read/Write): Three-State Access
—2WE Mode—

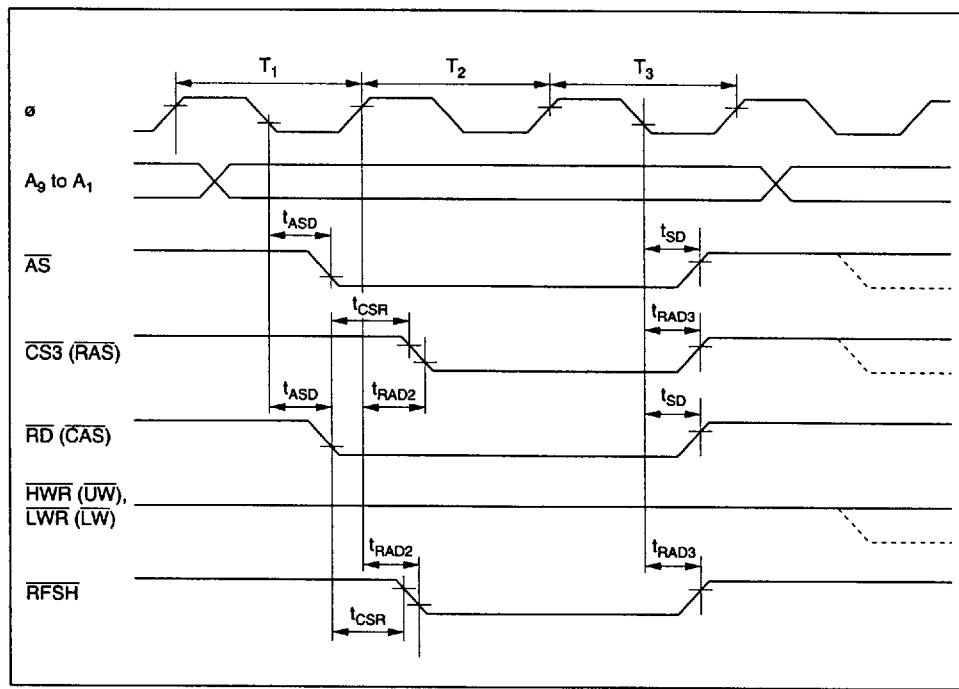


Figure 20-8 DRAM Bus Timing (Refresh Cycle): Three-State Access
— 2WE Mode —

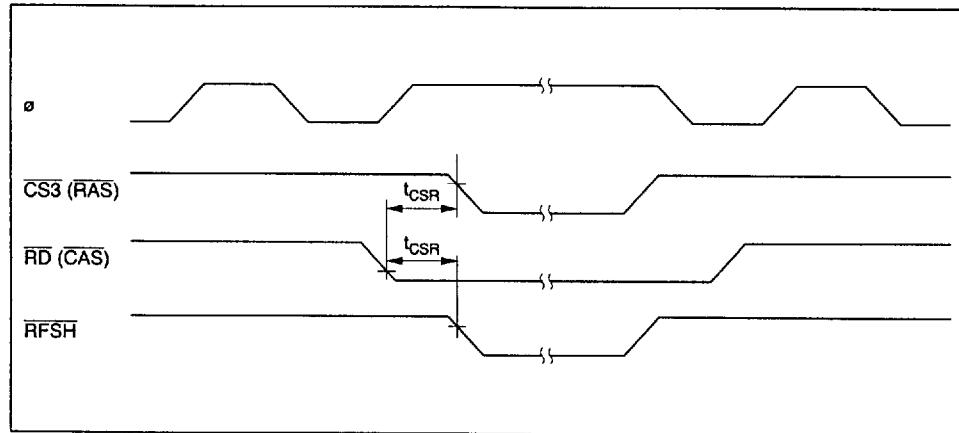


Figure 20-9 DRAM Bus Timing (Self-Refresh Mode)
— 2WE Mode —

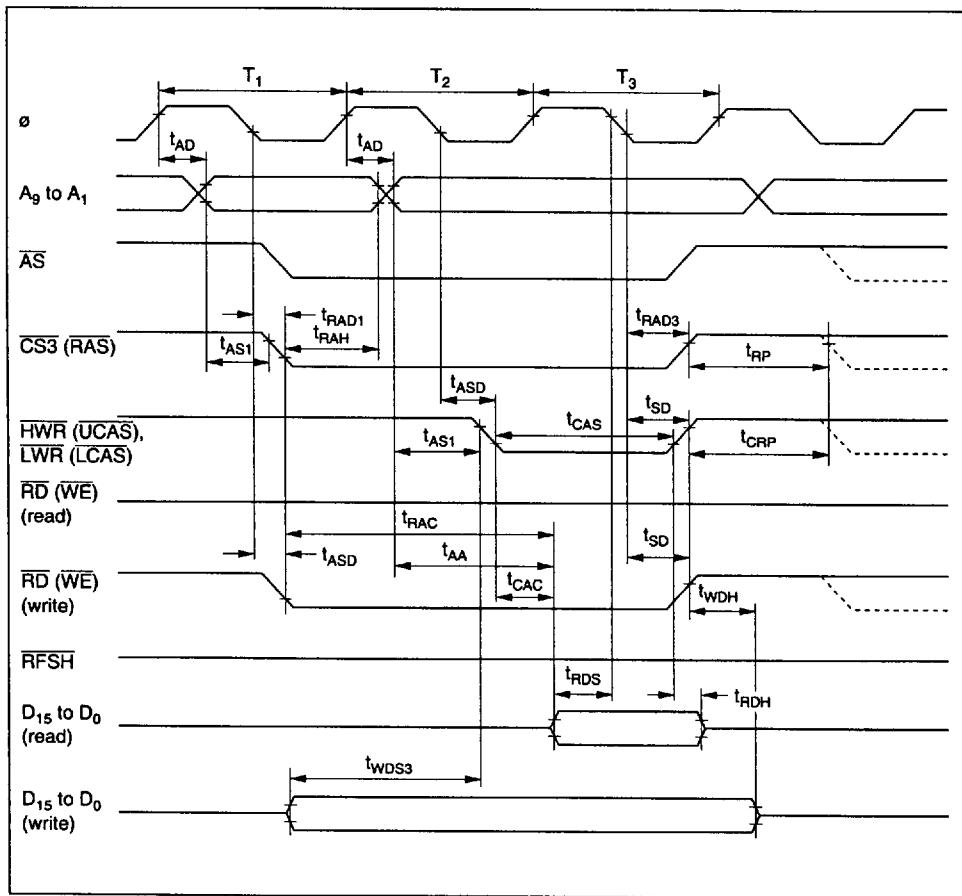


Figure 20-10 DRAM Bus Timing (Read/Write): Three-State Access
— 2CAS Mode —

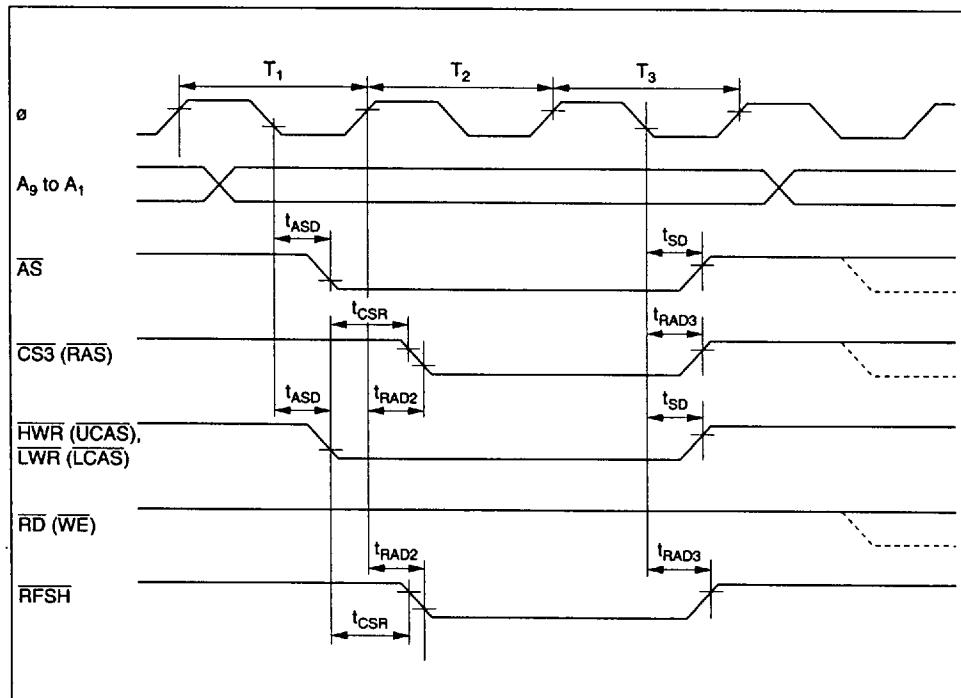


Figure 20-11 DRAM Bus Timing (Refresh Cycle): Three-State Access
— 2CAS Mode —

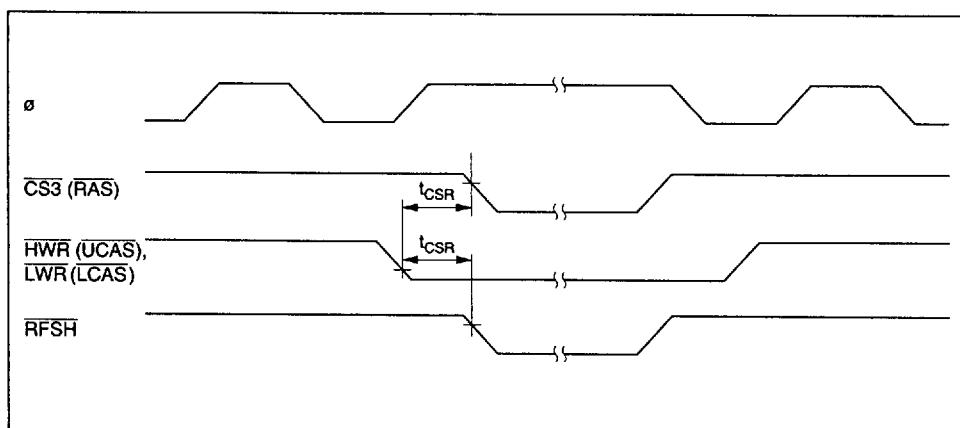


Figure 20-12 DRAM Bus Timing (Self-Refresh Mode)
— 2CAS Mode —

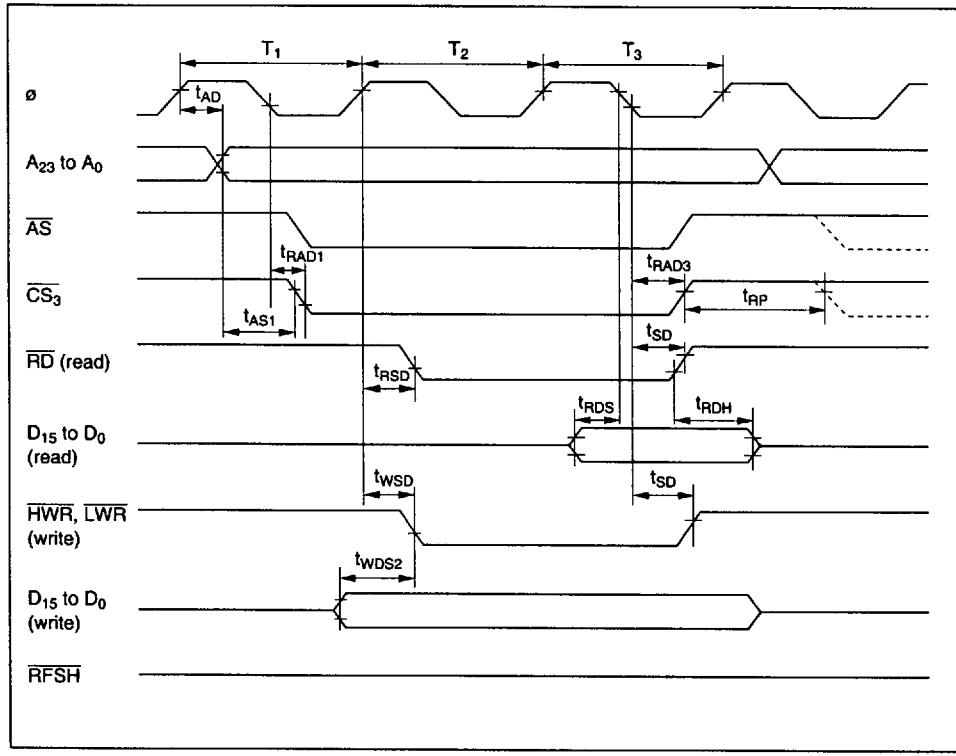


Figure 20-13 PSRAM Bus Timing (Read/Write): Three-State Access

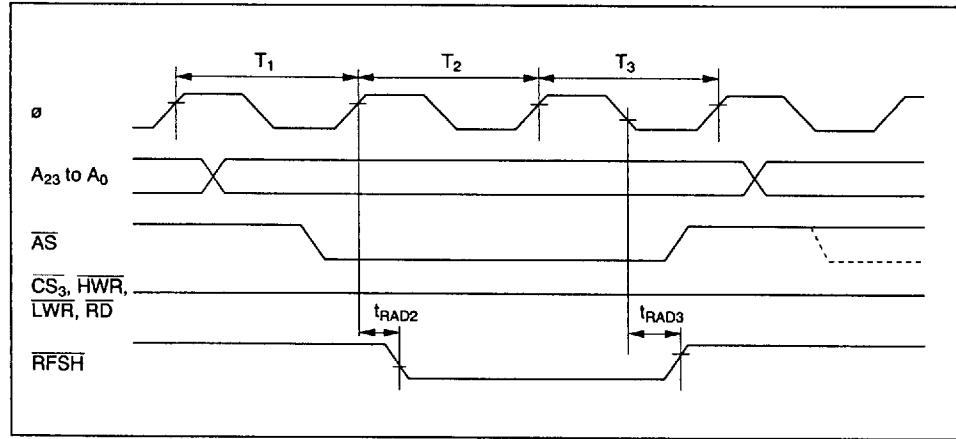


Figure 20-14 PSRAM Bus Timing (Refresh Cycle): Three-State Access

20.3.3 Control Signal Timing

Control signal timing is shown as follows:

- Reset input timing

Figure 20-15 shows the reset input timing.

- Reset output timing

Figure 20-16 shows the reset output timing.

- Interrupt input timing

Figure 20-17 shows the input timing for NMI and $\overline{\text{IRQ}}_5$ to $\overline{\text{IRQ}}_0$.

- Bus-release mode timing

Figure 20-18 shows the bus-release mode timing.

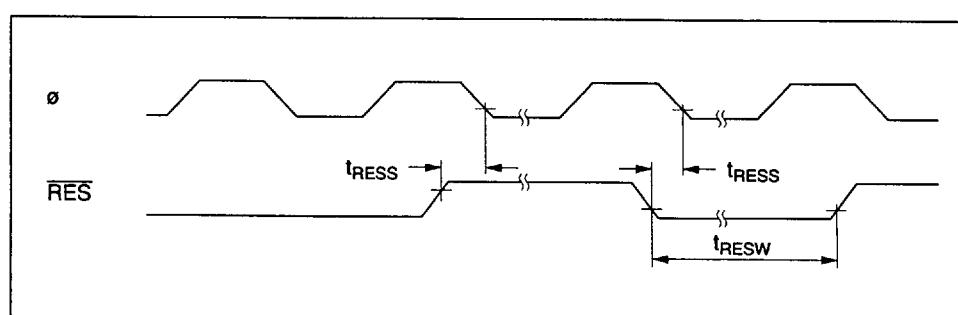


Figure 20-15 Reset Input Timing

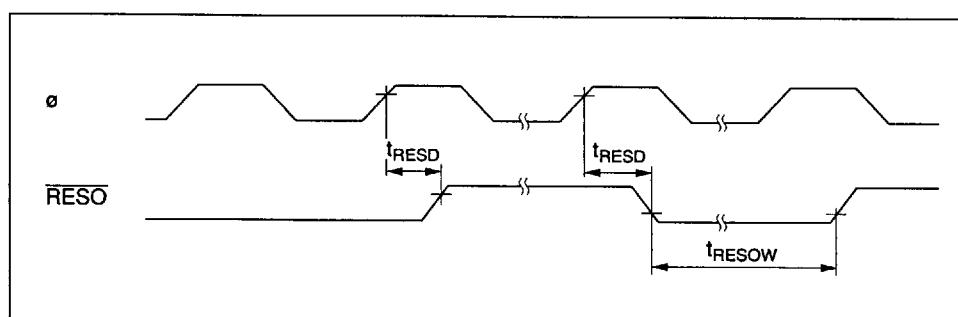


Figure 20-16 Reset Output Timing

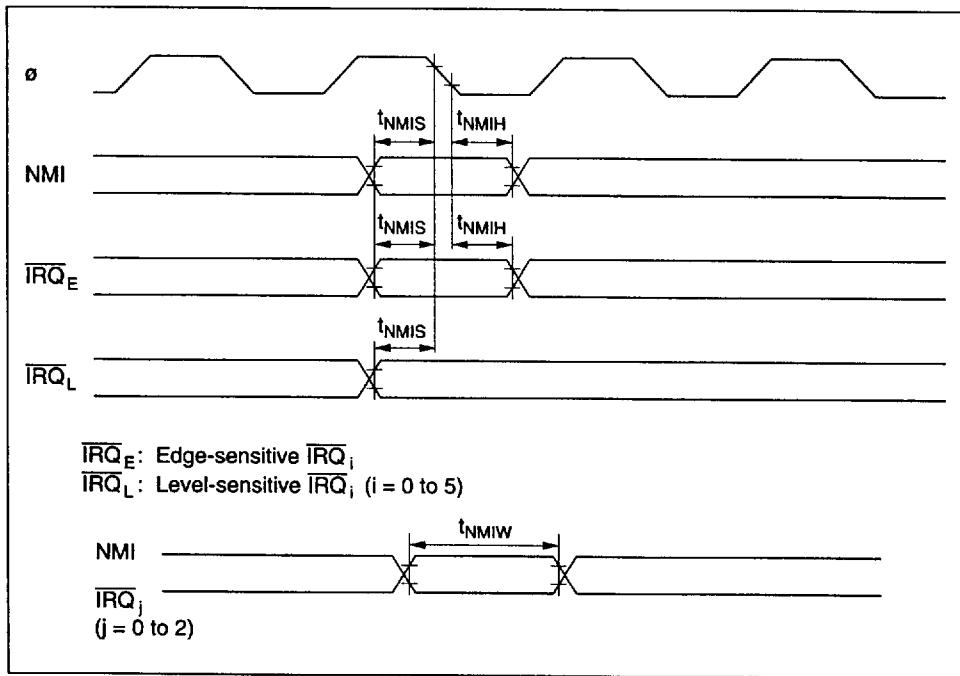


Figure 20-17 Interrupt Input Timing

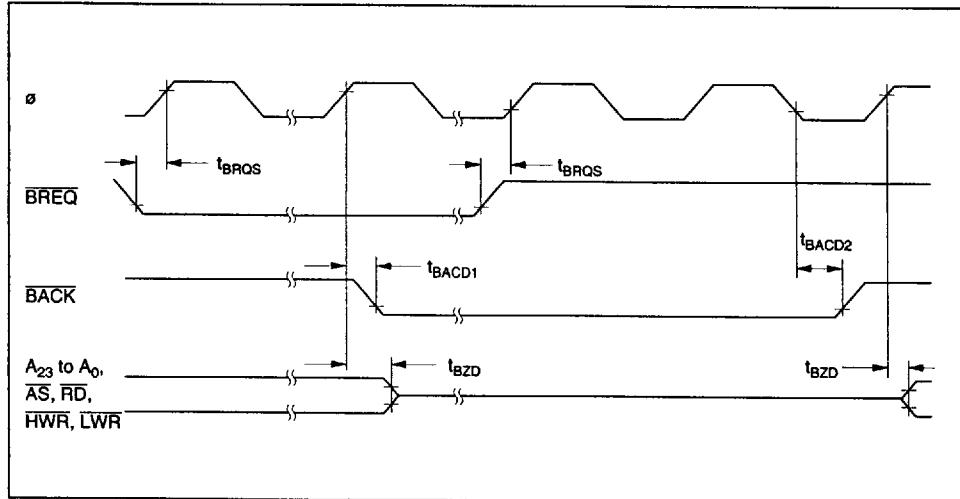


Figure 20-18 Bus-Release Mode Timing

20.3.4 Clock Timing

Clock timing is shown as follows:

- Oscillator settling timing

Figure 20-19 shows the oscillator settling timing.

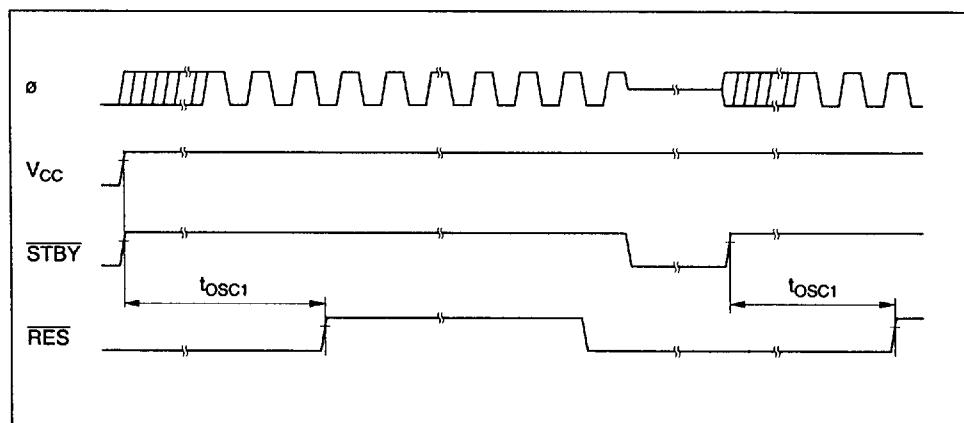


Figure 20-19 Oscillator Settling Timing

20.3.5 TPC and I/O Port Timing

TPC and I/O port timing is shown as follows.

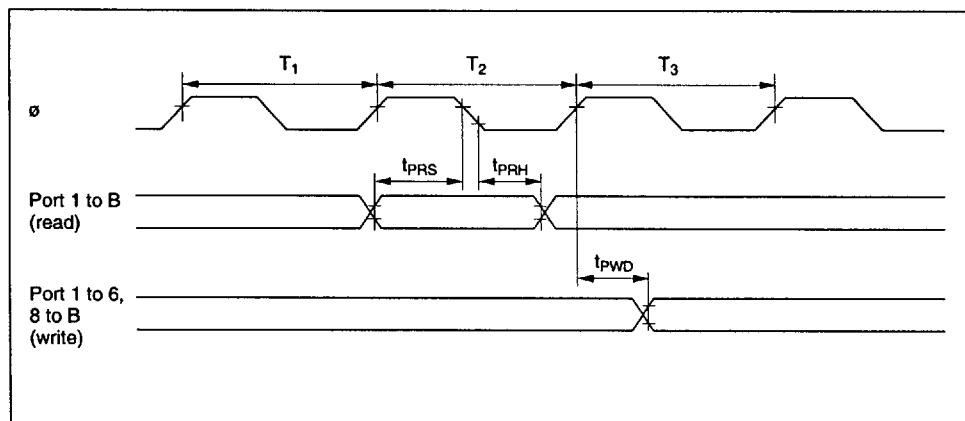


Figure 20-20 TPC and I/O Port Input/Output Timing

20.3.6 ITU Timing

ITU timing is shown as follows:

- ITU input/output timing

Figure 20-21 shows the ITU input/output timing.

- ITU external clock input timing

Figure 20-22 shows the ITU external clock input timing.

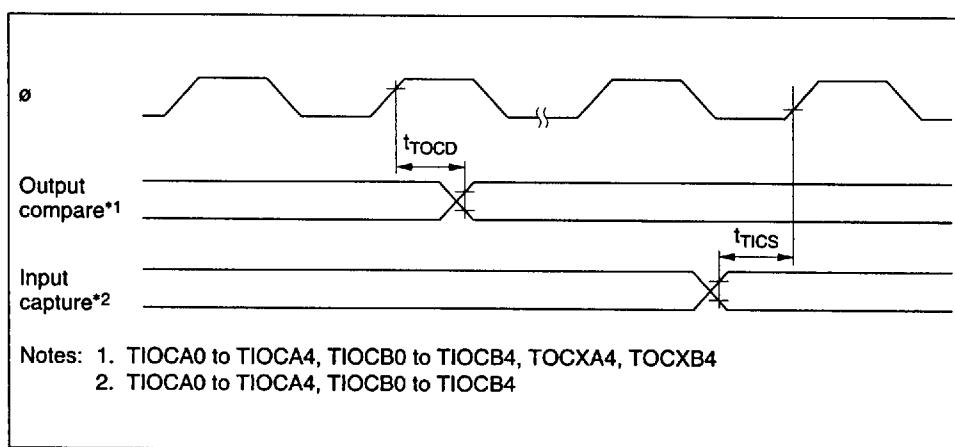


Figure 20-21 ITU Input/Output Timing

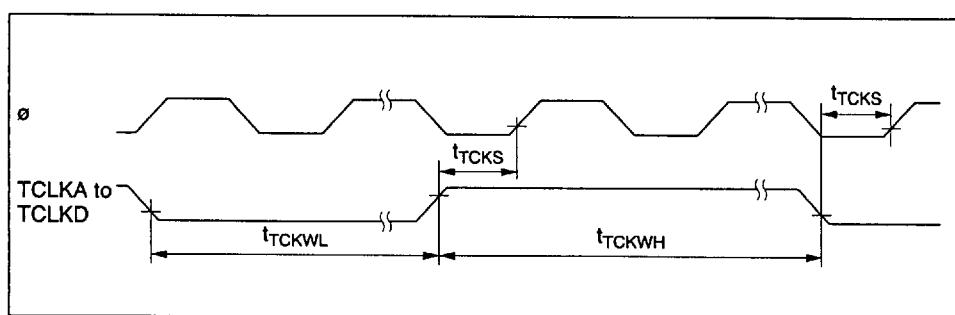


Figure 20-22 ITU Clock Input Timing

20.3.7 SCI Input/Output Timing

SCI timing is shown as follows:

- SCI input clock timing

Figure 20-23 shows the SCI input clock timing.

- SCI input/output timing (synchronous mode)

Figure 20-24 shows the SCI input/output timing in synchronous mode.

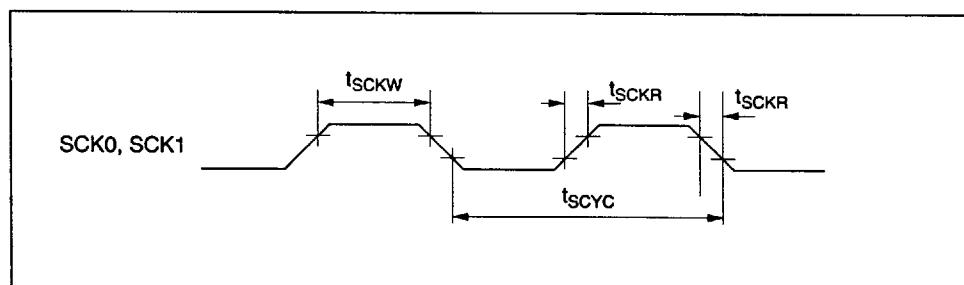


Figure 20-23 SCI Input Clock Timing

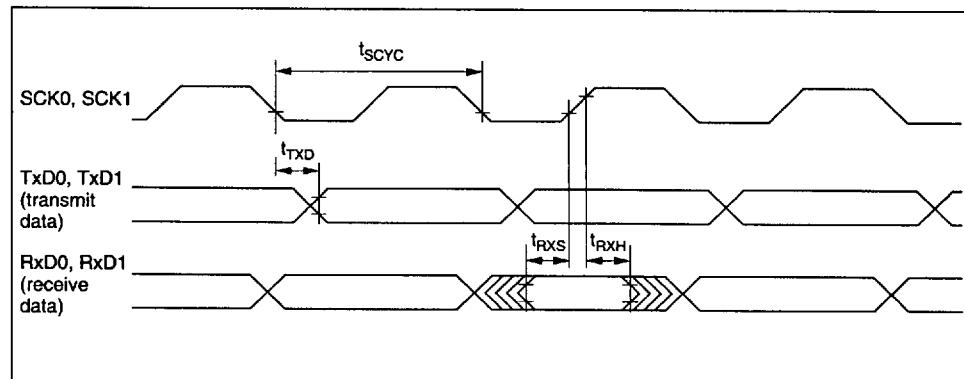


Figure 20-24 SCI Input/Output Timing in Synchronous Mode

20.3.8 DMAC Timing

DMAC timing is shown as follows.

- DMAC $\overline{\text{TEND}}$ output timing for 2 state access

Figure 20-25 shows the DMAC $\overline{\text{TEND}}$ output timing for 2 state access.

- DMAC $\overline{\text{TEND}}$ output timing for 3 state access

Figure 20-26 shows the DMAC $\overline{\text{TEND}}$ output timing for 3 state access.

- DMAC $\overline{\text{DREQ}}$ input timing

Figure 20-27 shows DMAC $\overline{\text{DREQ}}$ input timing.

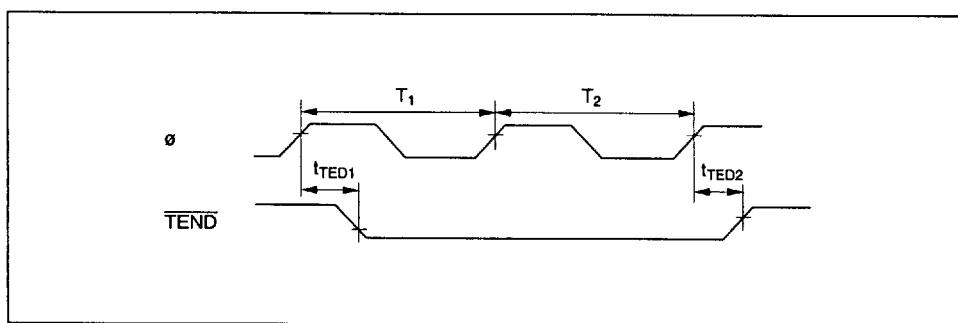


Figure 20-25 DMAC $\overline{\text{TEND}}$ Output Timing for 2 State Access

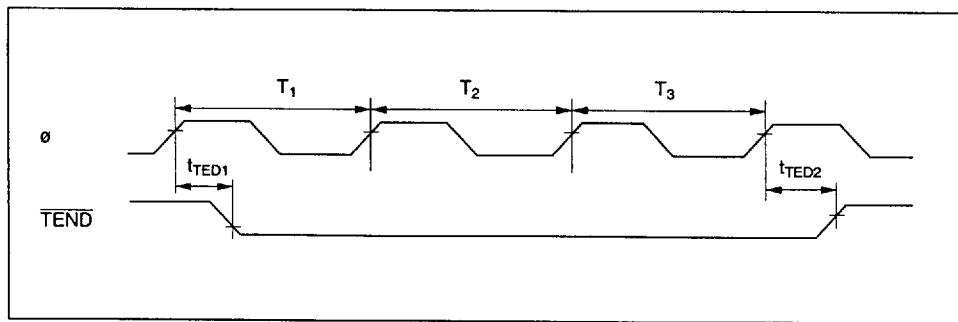


Figure 20-26 DMAC $\overline{\text{TEND}}$ Output Timing for 3 State Access

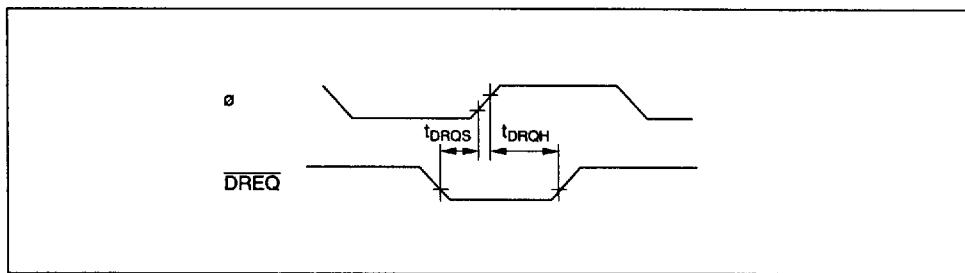


Figure 20-27 DMAC \overline{DREQ} Input Timing